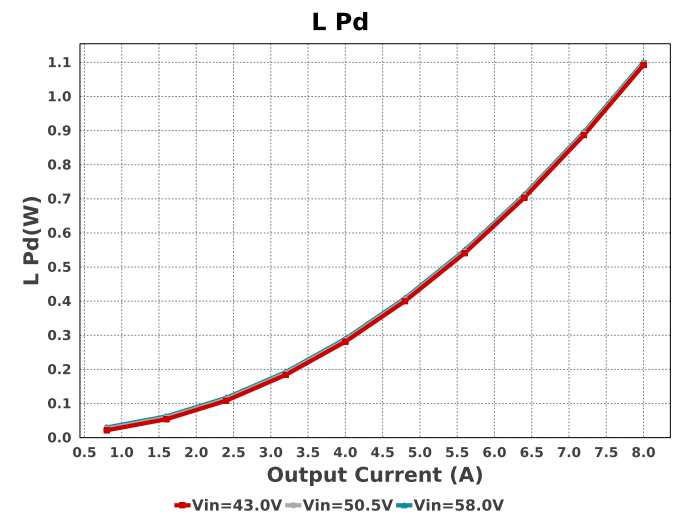
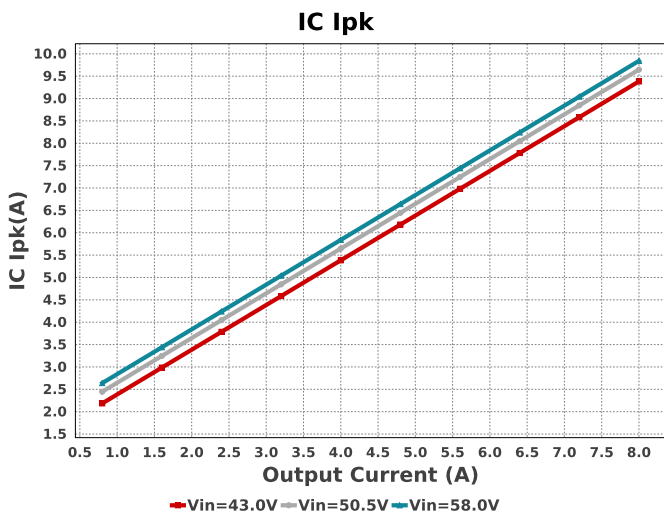
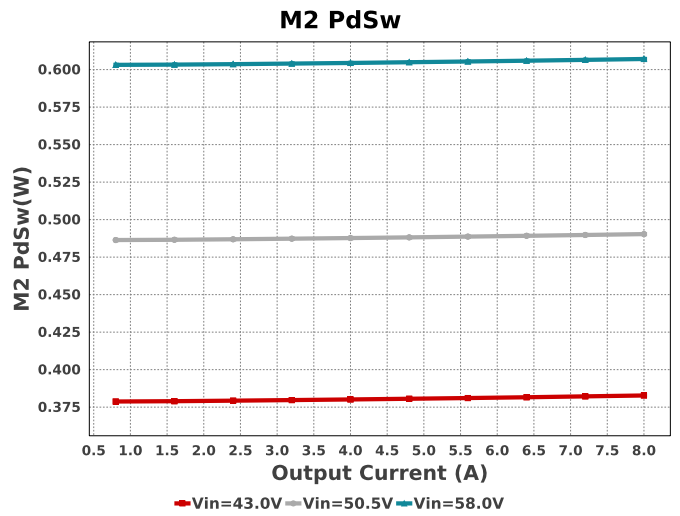
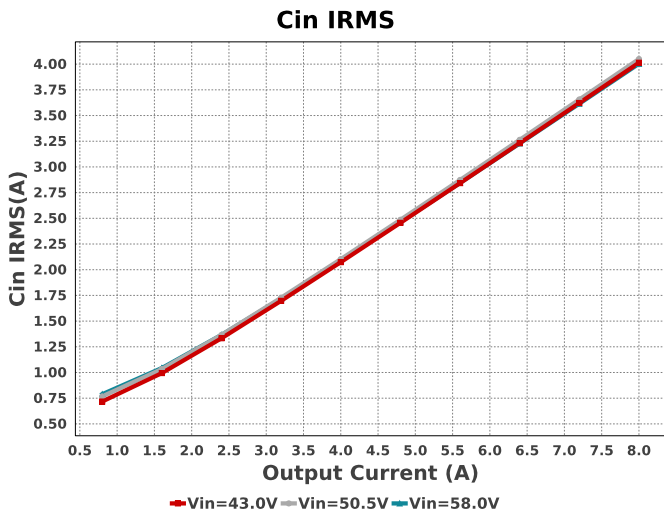
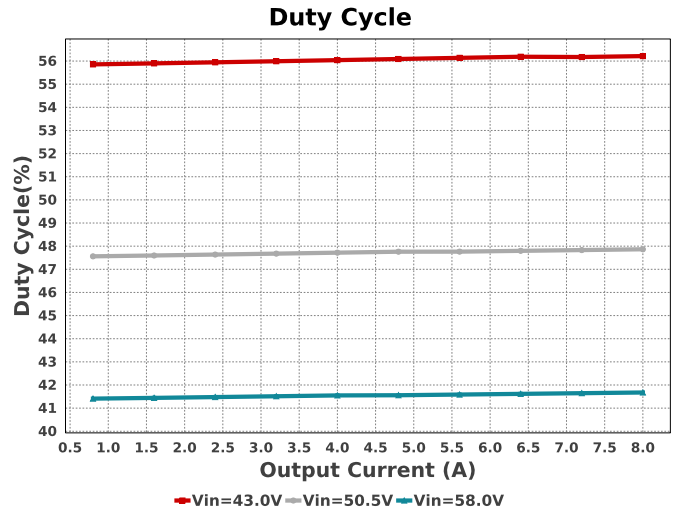
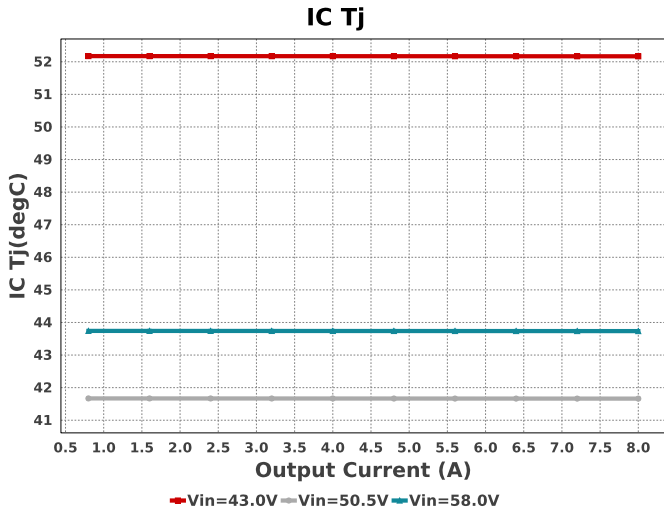
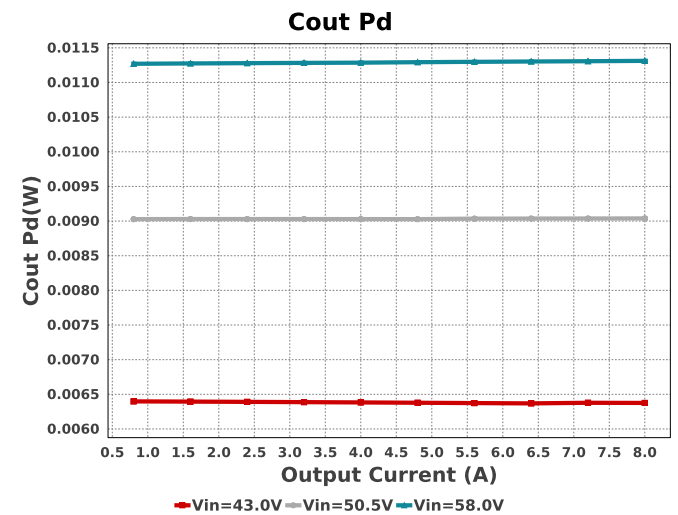
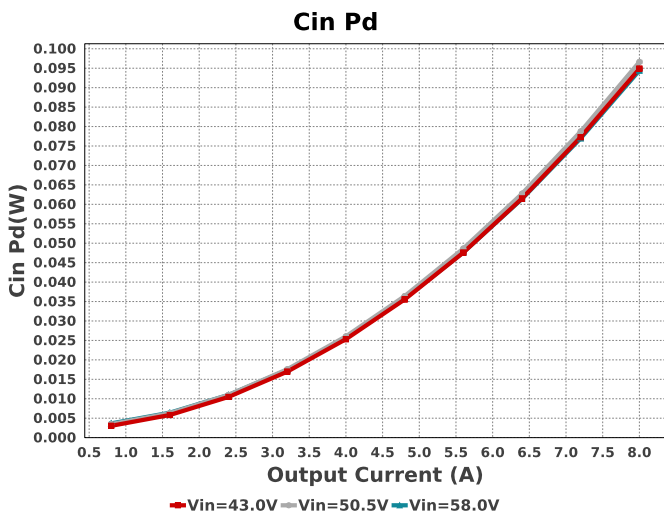
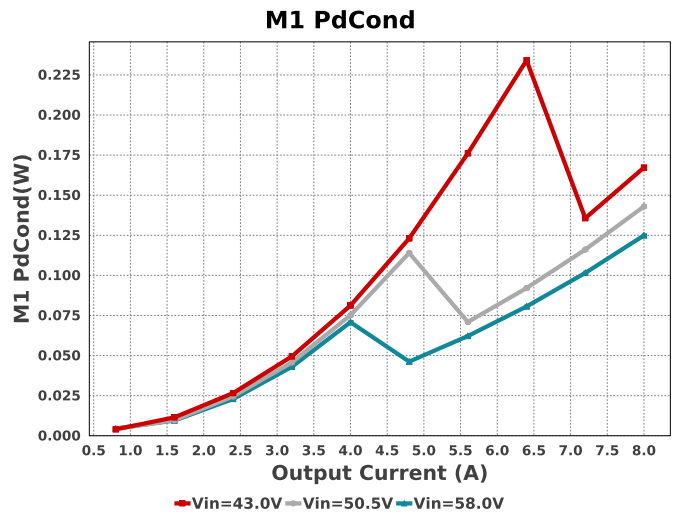
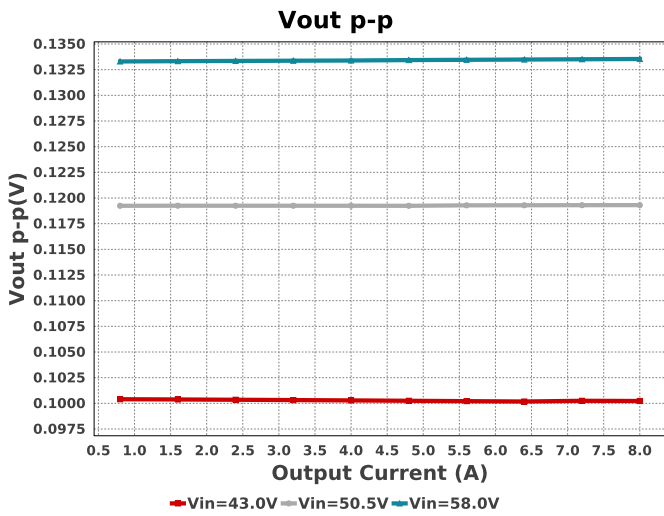
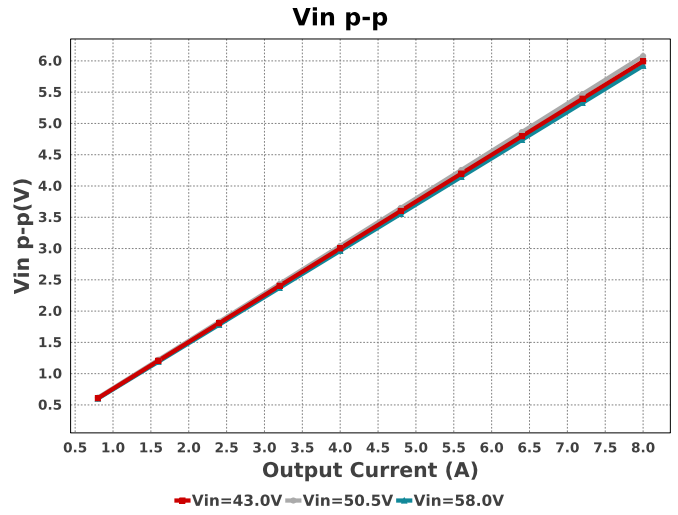
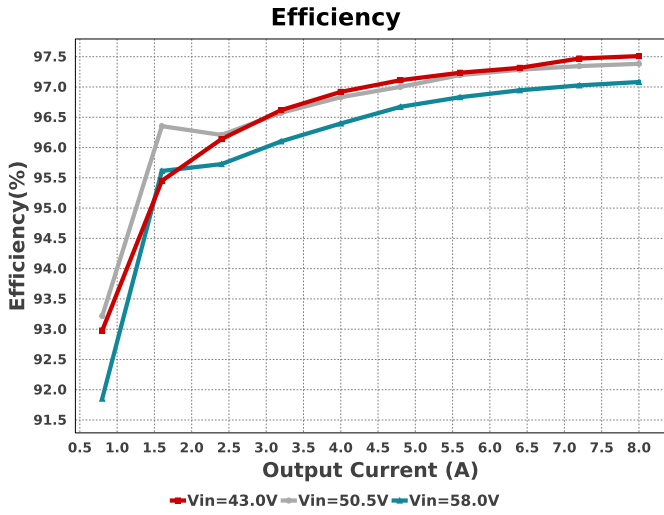
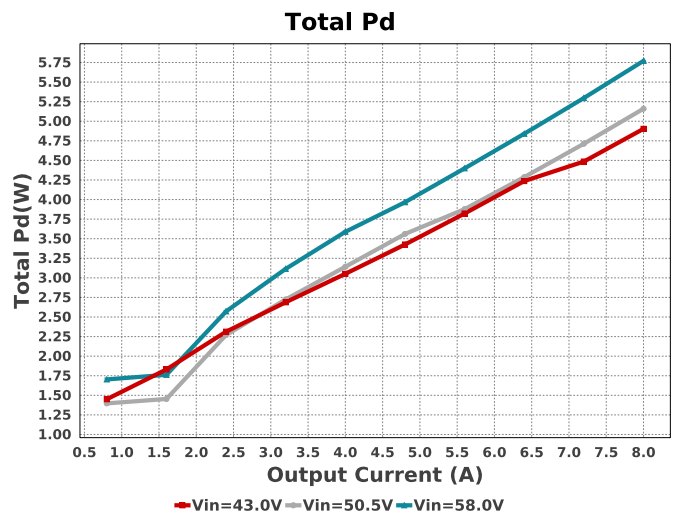
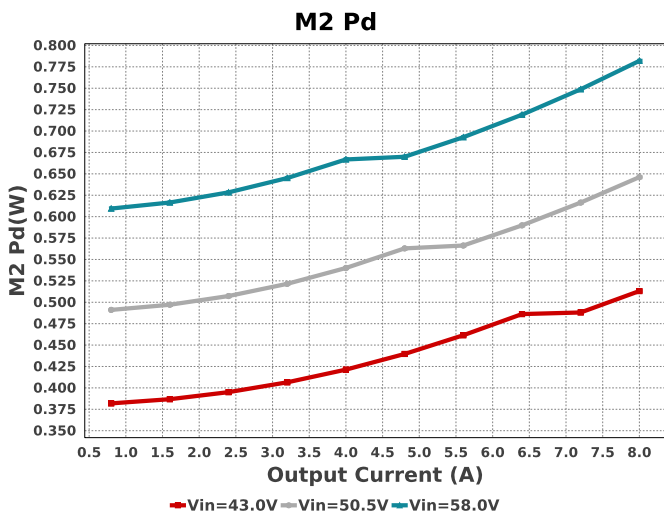
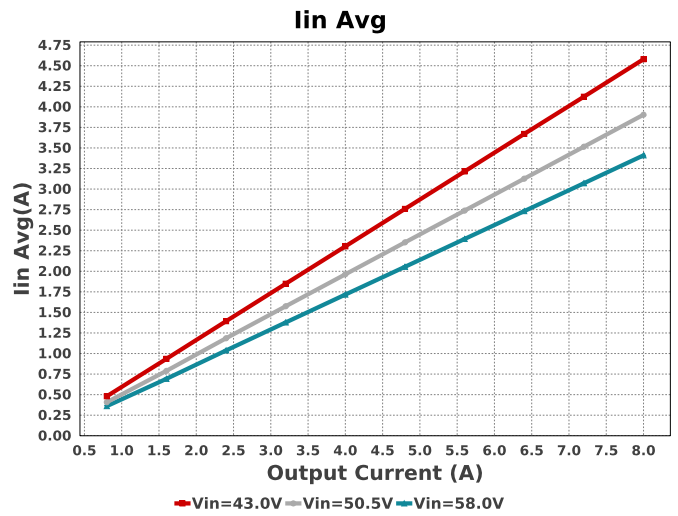
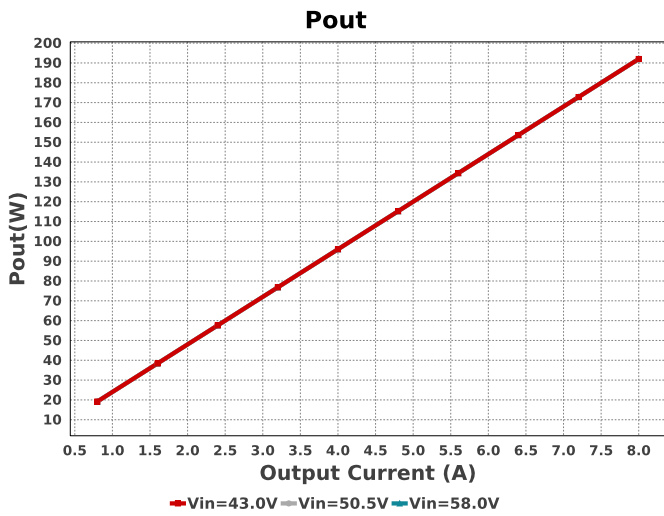
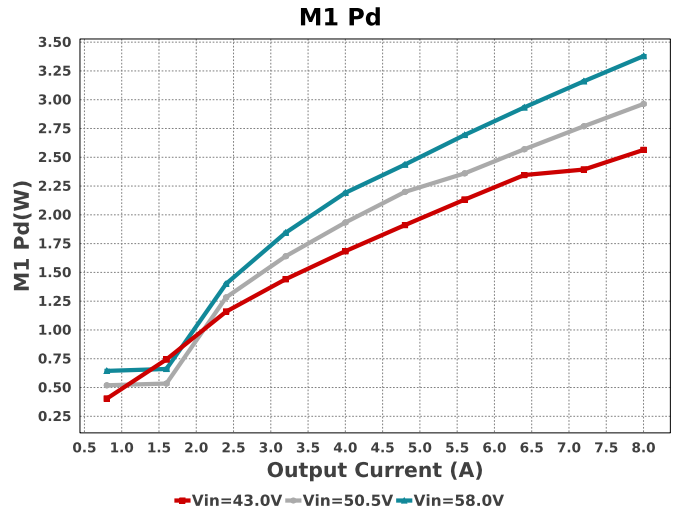
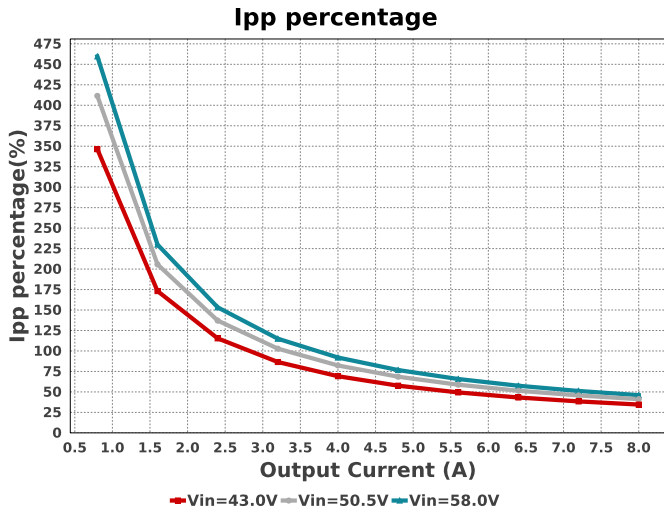


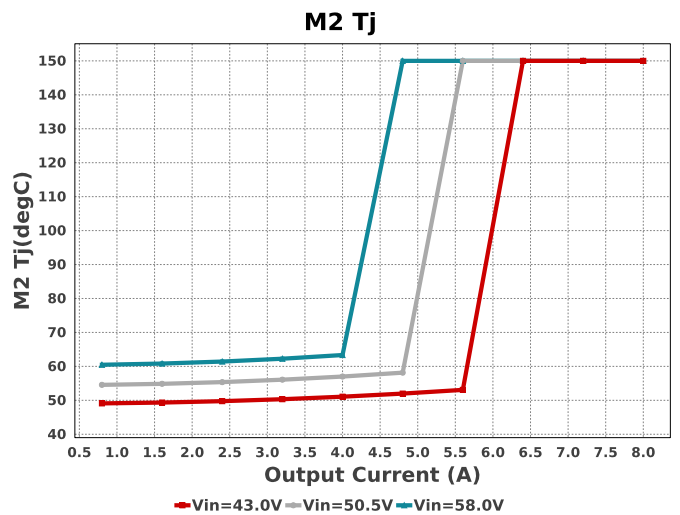
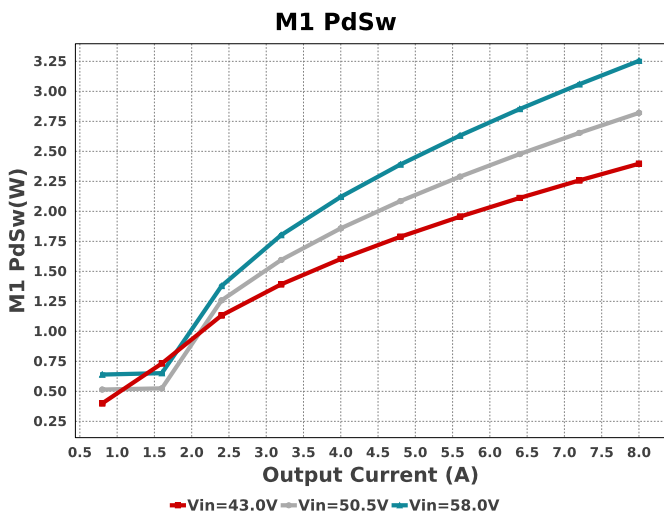
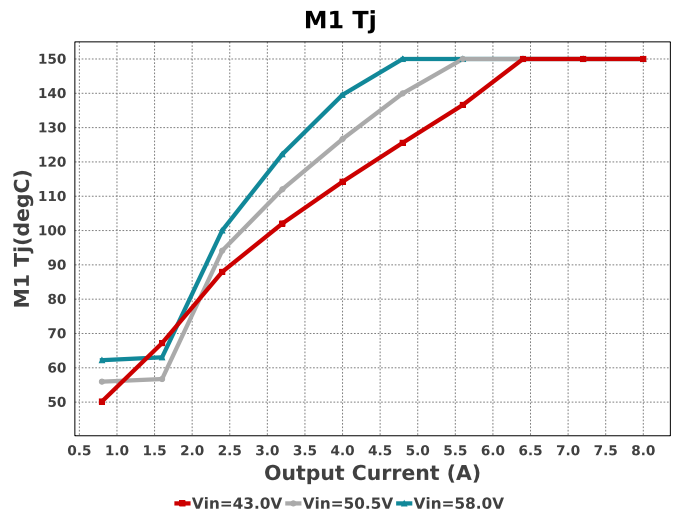
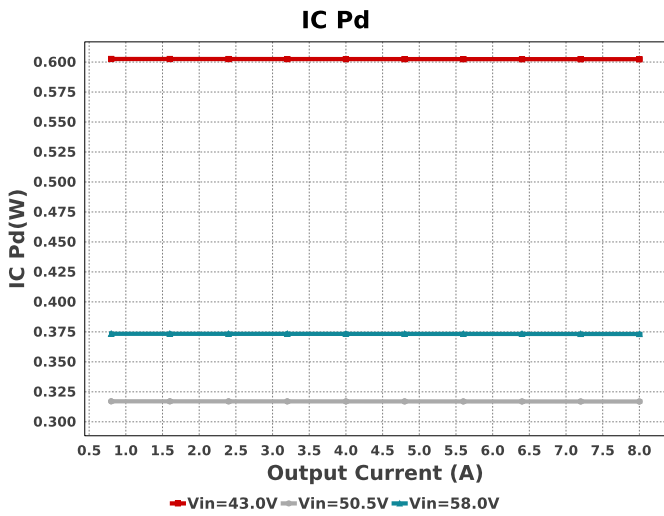
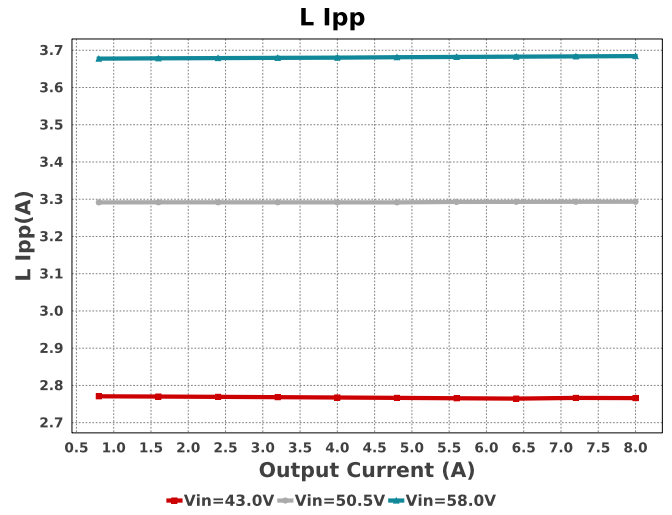
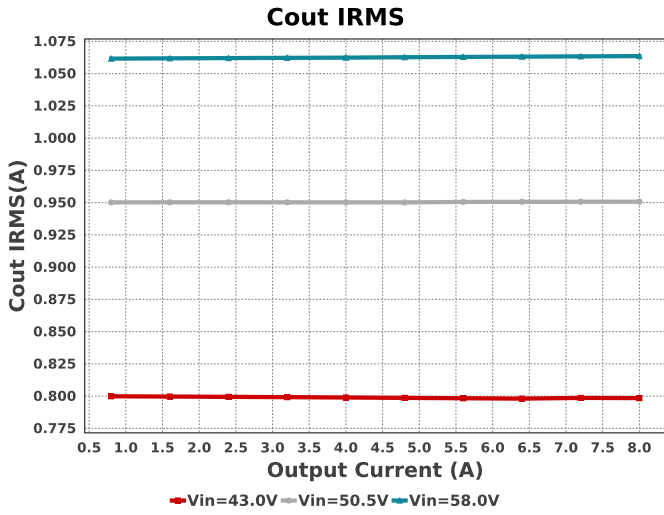


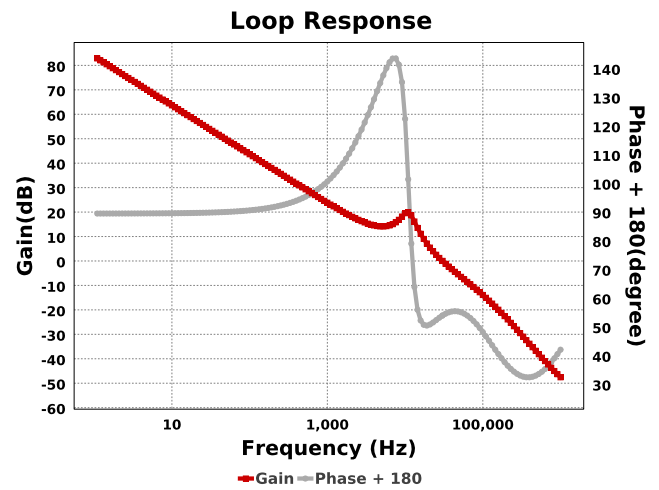
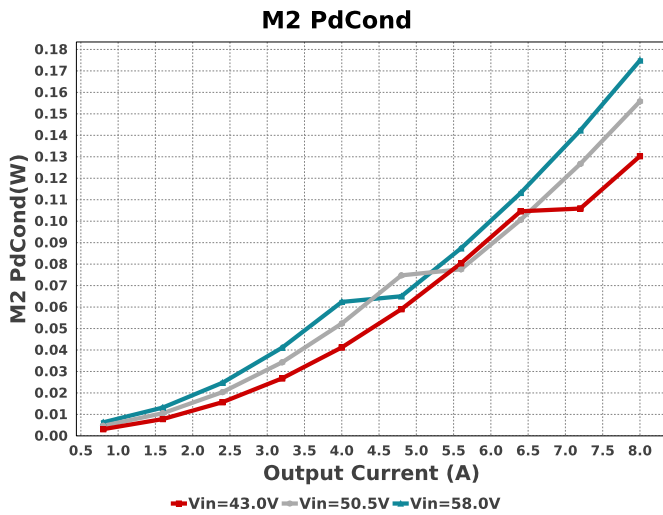
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cvin	TDK	C1608X7S2A104K080AB Series= X7S	Cap= 100.0 nF ESR= 49.59 mOhm VDC= 100.0 V IRMS= 751.62 mA	1	\$0.03	 0603 5 mm <sup>2</sup>
L1	Coilcraft	XAL1010-153MEB	L= 15.0 µH 16.9 mOhm	1	\$1.71	 XAL1010 160 mm <sup>2</sup>
M1	Texas Instruments	CSD19502Q5B	VdsMax= 80.0 V IdsMax= 100.0 Amps	1	\$0.74	DQK0006C 9 mm <sup>2</sup>
M2	Texas Instruments	CSD19502Q5B	VdsMax= 80.0 V IdsMax= 100.0 Amps	1	\$0.74	DQK0006C 9 mm <sup>2</sup>
Rcomp1	Vishay-Dale	CRCW04022K80FKED Series= CRCW..e3	Res= 2.8 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm <sup>2</sup>
Rcomp2	Vishay-Dale	CRCW040216R5FKED Series= CRCW..e3	Res= 16.5 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm <sup>2</sup>
Rfbb	Vishay-Dale	CRCW0402619RFKED Series= CRCW..e3	Res= 619.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm <sup>2</sup>
Rfbt	Yageo	RC0603FR-0718KL Series= ?	Res= 18.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
Rilim	Vishay-Dale	CRCW0805576RFKEA Series= CRCW..e3	Res= 576.0 Ohm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	 0805 7 mm <sup>2</sup>
Rpgood	Yageo	RC0603FR-0720KL Series= ?	Res= 20.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
Rt	Vishay-Dale	CRCW040239K2FKED Series= CRCW..e3	Res= 39.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm <sup>2</sup>
Ruv1	Vishay-Dale	CRCW0603215KFKEA Series= CRCW..e3	Res= 215.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
Ruv2	Yageo	RC0603FR-077K68L Series= ?	Res= 7.68 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
Rvcc	Yageo	RC0603FR-0720KL Series= ?	Res= 20.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
Rvin	Vishay-Dale	CRCW06032R10FKEA Series= CRCW..e3	Res= 2.1 Ohm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm <sup>2</sup>
U1	Texas Instruments	LM5146RGYR	Switcher	1	\$1.58	 RGY0020B 25 mm <sup>2</sup>











## Operating Values

#	Name	Value	Category	Description
1.	BOM Count	25		Total Design BOM count
2.	Total BOM	\$7.261		Total BOM Cost
3.	Cin IRMS	4.003 A	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	94.405 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	1.064 A	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	11.312 mW	Capacitor	Output capacitor power dissipation
7.	IC Ipk	9.842 A	IC	Peak switch current in IC
8.	IC Pd	373.23 mW	IC	IC power dissipation
9.	IC Tj	43.735 degC	IC	IC junction temperature
10.	IC Tolerance	8.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA	36.8 degC/W	IC	IC junction-to-ambient thermal resistance
12.	Iin Avg	3.41 A	IC	Average input current
13.	Ipp percentage	46.054 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	3.684 A	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	1.101 W	Inductor	Inductor power dissipation
16.	M1 Pd	3.379 W	Mosfet	M1 MOSFET total power dissipation
17.	M1 PdCond	124.92 mW	Mosfet	M1 MOSFET conduction losses
18.	M1 PdSw	3.254 W	Mosfet	M1 MOSFET switching losses
19.	M1 Tj	150.0 degC	Mosfet	M1 MOSFET junction temperature
20.	M2 Pd	781.96 mW	Mosfet	M2 MOSFET total power dissipation
21.	M2 PdCond	174.89 mW	Mosfet	M2 MOSFET conduction losses
22.	M2 PdSw	607.07 mW	Mosfet	M2 MOSFET switching losses
23.	M2 Tj	150.0 degC	Mosfet	M2 MOSFET junction temperature
24.	Cin Pd	94.405 mW	Power	Input capacitor power dissipation
25.	Cout Pd	11.312 mW	Power	Output capacitor power dissipation
26.	IC Pd	373.23 mW	Power	IC power dissipation
27.	L Pd	1.101 W	Power	Inductor power dissipation
28.	M1 Pd	3.379 W	Power	M1 MOSFET total power dissipation
29.	M1 PdCond	124.92 mW	Power	M1 MOSFET conduction losses
30.	M1 PdSw	3.254 W	Power	M1 MOSFET switching losses
31.	M2 Pd	781.96 mW	Power	M2 MOSFET total power dissipation
32.	M2 PdCond	174.89 mW	Power	M2 MOSFET conduction losses
33.	M2 PdSw	607.07 mW	Power	M2 MOSFET switching losses
34.	Total Pd	5.771 W	Power	Total Power Dissipation
35.	Duty Cycle	41.676 %	System	Duty cycle
36.	Efficiency	97.082 %	System	Steady state efficiency
37.	FootPrint	349.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
38.	Frequency	255.102 kHz	System	Switching frequency
39.	Iout	8.0 A	System	Iout operating point
40.	Mode	FCCM	System	Conduction Mode
41.	Pout	192.0 W	System	Total output power
42.	Vin	58.0 V	System	Vin operating point

#	Name	Value	Category	Description
43.	Vin p-p	5.922 V	System Information	Peak-to-peak input voltage
44.	Vout	24.0 V	System Information	Operational Output Voltage
45.	Vout Actual	24.063 V	System Information	Vout Actual calculated based on selected voltage divider resistors
46.	Vout Tolerance	2.973 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
47.	Vout p-p	133.541 mV	System Information	Peak-to-peak output ripple voltage

## Design Inputs

Name	Value	Description
Iout	8.0	Maximum Output Current
VinMax	58.0	Maximum input voltage
VinMin	43.0	Minimum input voltage
Vout	24.0	Output Voltage
base_pn	LM5146	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature



## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 43.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

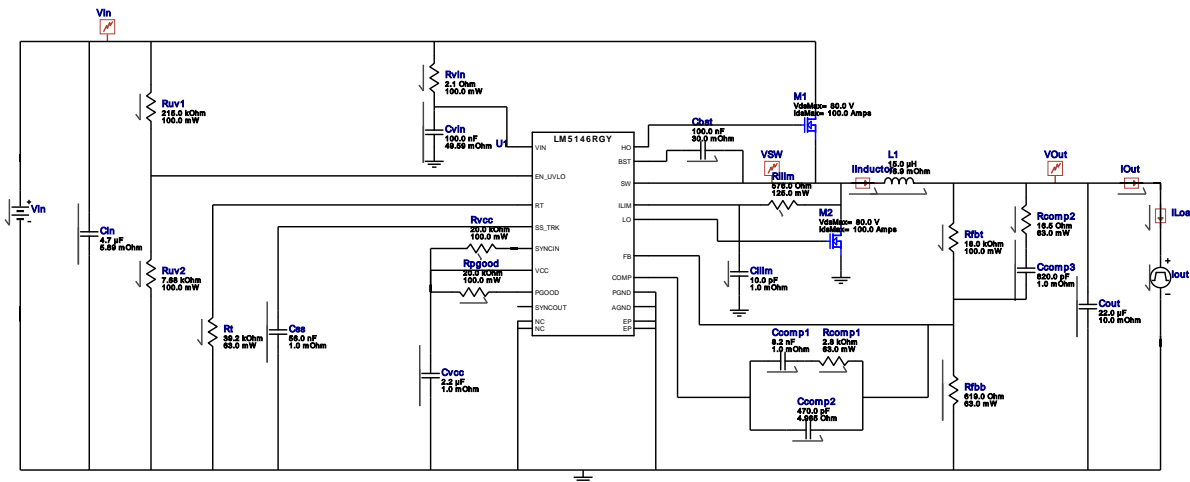


# WEBENCH® Electrical Simulation Report

Design Id = 1

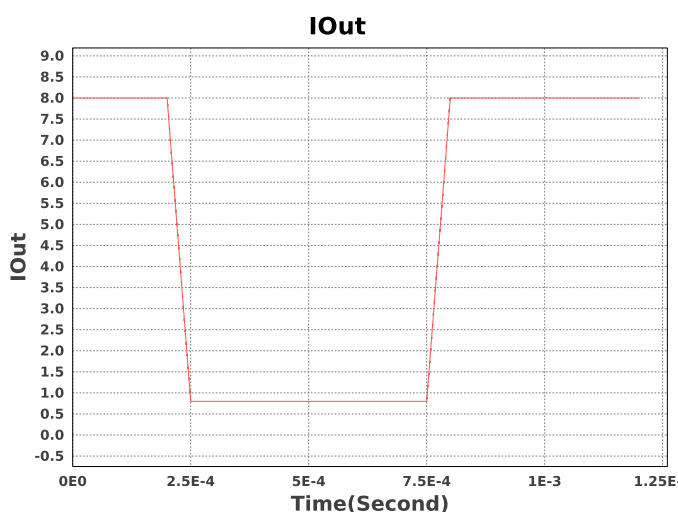
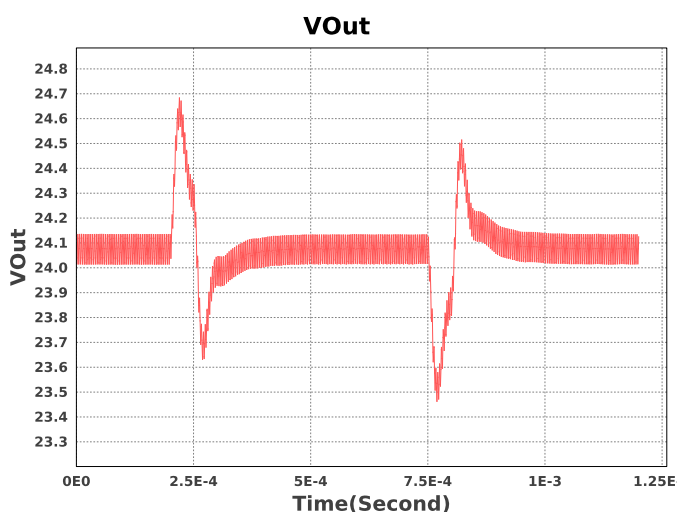
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Simulation Type = Load Transient



## Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Css	IC	Initial condition	1 V
2.	L1	IC	Initial condition	8.0 A
3.	Cvcc	IC	Initial Voltage	3.3 V
4.	Cout	IC	Initial condition	24.0 V
5.	Iout	signal_type	Signal Type	PULSE
		I1	Initial Load Current	8.0 A
		I2	Minimum Load Current	0.8 A
		Td	Initial Time Delay	2.0E-4 s
		Tf	Fall Time	50u s
		Tr	Rise Time	50u s
		Pw	Pulse Width	5.0E-4 s



## Design Assistance

1. Master key : 71590F7B87C1D65681CB58F7954C2616[v1]

2. LM5146 Product Folder : <http://www.ti.com/product/lm5146> : contains the data sheet and other resources.

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